

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	SANJIV SIRPAL	08/12/2015
	MOHAMMED SELIM	08/12/2015
	ALEXANDER DE PAZ	08/12/2015
	SALVADOR SOTO	08/12/2015
	SERGII GRYSSENKO	08/12/2015
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<b>State/Country:</b>	CHINA	
<b>Postal Code:</b>	266555	
<b>PROPERTY NUMBERS Total: 1</b>		

PATENT

Property Type	Number
Application Number:	14829893

**CORRESPONDENCE DATA**

**Fax Number:**

*Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.*

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<b>ATTORNEY DOCKET NUMBER:</b>	249311.000008
<b>NAME OF SUBMITTER:</b>	JOHN P. TERESINSKI
<b>SIGNATURE:</b>	/John P. Teresinski/
<b>DATE SIGNED:</b>	08/02/2016

**Total Attachments: 3**

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**ASSIGNMENT BY INVENTORS**

**THIS ASSIGNMENT**, made by Sanjiv SIRPAL, whose mailing address is: c/o Jamdeo Canada Ltd., 2305 Wyecroft Road, Suite 201, Oakville, Ontario, L6L6R2, Canada; Mohammed SELIM, whose mailing address is: c/o Jamdeo Canada Ltd., 2305 Wyecroft Road, Suite 201, Oakville, Ontario, L6L6R2, Canada; Alexander DE PAZ, whose mailing address is: c/o Jamdeo Canada Ltd., 2305 Wyecroft Road, Suite 201, Oakville, Ontario, L6L6R2, Canada; Salvador SOTO, whose mailing address is: c/o Jamdeo Canada Ltd., 2305 Wyecroft Road, Suite 201, Oakville, Ontario, L6L6R2, Canada; and Sergii GRYSSENKO, whose mailing address is: c/o Jamdeo Canada Ltd., 2305 Wyecroft Road, Suite 201, Oakville, Ontario, L6L6R2, Canada; (hereinafter referred to as "Assignors")

**WHEREAS**, Assignors have invented certain new and useful improvements in **SYSTEM AND METHODS FOR CARD ELEMENT APPLICATION OPERATION**, set forth in a Patent application for Letters Patent of the United States, already filed on August 19, 2015 as U.S. Application Serial No. 14/829,893; and

**WHEREAS**, Jamdeo Canada Ltd., 2305 Wyecroft Road, Suite 201, Oakville, Ontario, L6L 6R2, Canada; Hisense USA Corp., 7310 McGinnis Ferry Road, Suwanee, GA 30024; Hisense Electric Co., Ltd., No.218 Qianwangang Road, Economic and Technical Development Zone, Qingdao, Shandong, 266555 China; and Hisense International Co., Ltd., No.218 Qianwangang Road, Qingdao, P.R.C. China (hereinafter referred to "ASSIGNEES"), are desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefore in the United States and in any and all foreign countries;

**NOW, THEREFORE**, in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, Assignors, as sole and joint inventors as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, their successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof,

and in and to any and all Letters Patent of the United States and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other International agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me individually and/or jointly with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and Assignors hereby authorize and request the Commissioner of Patents to issue the United States Letters Patent to said ASSIGNEE the whole right, title and interest thereto;

AND Assignors further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or their designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

AND Assignors further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at their own expense;

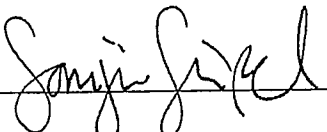
AND Assignors further agree that ASSIGNEE will, upon request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

AND Assignors hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;


AND Assignors hereby authorize and request the attorneys of record in this application to insert the execution date, serial number and filing date of this application in the spaces that follow:

Application Serial Number: 14/829,893 Filing Date: August 19, 2015


This Assignment is being executed on the date indicated below.

  
\_\_\_\_\_  
Sanjiv SIRPAL


Dated: Aug 12/2015

  
\_\_\_\_\_  
Mohammed SELIM


Dated: Aug 12 / 2015

  
\_\_\_\_\_  
Alexander DE PAZ

Dated: Aug 12 2015

  
\_\_\_\_\_  
Salvador SOTO

Dated: Aug 12<sup>th</sup> / 2015

  
\_\_\_\_\_  
Sergii Grysenko

Dated: Aug 12, 2015